

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHING-YU CHOU	11/03/2006
YU-NING WANG	11/03/2006
RECEIVING PARTY DATA	
Name:	ICF Technology Co., Ltd.
Street Address:	4F, No. 24-1, Industry East 4th Rd.
City:	Hsinchu
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11557922
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	US10528
NAME OF SUBMITTER:	Jeffrey Todd Knapp
Total Attachments: 2	
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source=US10528061106ASM#page2.tif	

CH \$40.00 11557922

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. Ching-Yu Chou , residing at Hsinchu, Taiwan
- 2. Yu-Ning Wang , residing at Hsinchu, Taiwan
- 3. _____ , residing at _____
- 4. _____ , residing at _____
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____


hereby sell(s), assign(s) and transfer(s) unto: ICF Technology CO., LTD. having a principal place of business at 4F, No.24-1, Industry East 4th Rd., Science-Based Industrial Park, Hsinchu City, Taiwan, R.O.C. hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as SUBSTRATE STRUCTURE WITH PATTERNED LAYER AND METHOD FOR MANUFACTURING SAME for which the undersigned

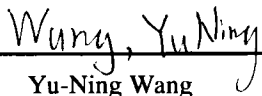
[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.  Nov. 3, 2006
Ching-Yu Chou inventor Date Witness

2.  Nov. 3, 2006
Yu-Ning Wang inventor Date Witness

3. _____
inventor Date Witness

4. _____
inventor Date Witness

5. _____
inventor Date Witness

6. _____
inventor Date Witness

7. _____
inventor Date Witness

8. _____
inventor Date Witness